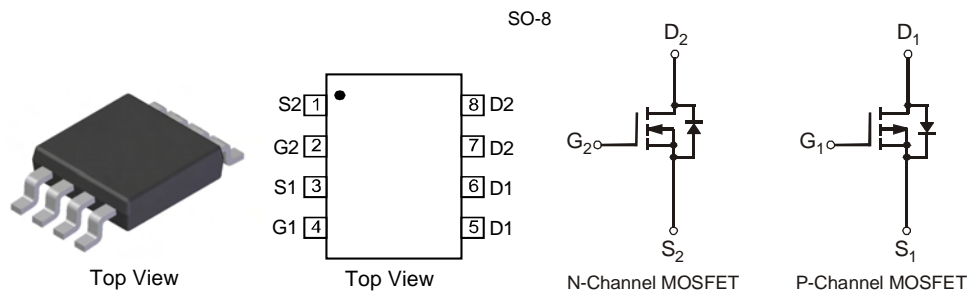


## Features

- Low On-Resistance
- N-Channel: 32mΩ @ 10V  
46mΩ @ 4.5V
- P-Channel: 39mΩ @ 10V  
53mΩ @ 4.5V
- Low Input Capacitance
- Fast Switching Speed
- Low Input/Output Leakage
- Complementary Pair MOSFET
- **Lead Free/RoHS Compliant (Note 1)**
- **"Green" Device (Note 2)**
- **Qualified to AEC-Q101 Standards for High Reliability**

## Mechanical Data

- Case: SO-8
- Case Material: Molded Plastic, "Green" Molding Compound. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals Connections: See Diagram
- Terminals: Finish - Matte Tin annealed over Copper lead frame. Solderable per MIL-STD-202, Method 208
- Marking Information: See Page 6
- Ordering Information: See Page 6
- Weight: 0.072 grams (approximate)



## Maximum Ratings N-CHANNEL – Q1 @ $T_A = 25^\circ\text{C}$ unless otherwise specified

Characteristic			Symbol	Value	Unit
Drain-Source Voltage			$V_{DSS}$	30	V
Gate-Source Voltage			$V_{GSS}$	$\pm 20$	V
Continuous Drain Current (Note 3)	Steady State	$T_A = 25^\circ\text{C}$	$I_D$	8.1	A
		$T_A = 85^\circ\text{C}$		5.1	
Pulsed Drain Current (Note 4)			$I_{DM}$	25	A

## Maximum Ratings P-CHANNEL – Q2 @ $T_A = 25^\circ\text{C}$ unless otherwise specified

Characteristic			Symbol	Value	Unit
Drain-Source Voltage			$V_{DSS}$	-30	V
Gate-Source Voltage			$V_{GSS}$	$\pm 20$	V
Continuous Drain Current (Note 3)	Steady State	$T_A = 25^\circ\text{C}$	$I_D$	-7.0	A
		$T_A = 85^\circ\text{C}$		-4.5	
Pulsed Drain Current (Note 4)			$I_{DM}$	-25	A

## Thermal Characteristics @ $T_A = 25^\circ\text{C}$ unless otherwise specified

Characteristic	Symbol	Value	Unit
Power Dissipation (Note 3)	$P_D$	2.5	W
Thermal Resistance, Junction to Ambient (Note 3)	$R_{\theta JA}$	50	$^\circ\text{C}/\text{W}$
Operating and Storage Temperature Range	$T_J, T_{STG}$	-55 to +150	$^\circ\text{C}$

- Notes:
1. No purposefully added lead.
  2. Diodes Inc.'s "Green" policy can be found on our website at [http://www.diodes.com/products/lead\\_free/index.php](http://www.diodes.com/products/lead_free/index.php).
  3. Device mounted on FR-4 PCB, with minimum recommended pad layout.
  4. Repetitive rating, pulse width limited by junction temperature.

**Electrical Characteristics N-CHANNEL – Q1** @ $T_A = 25^\circ\text{C}$  unless otherwise specified

Characteristic	Symbol	Min	Typ	Max	Unit	Test Condition
<b>OFF CHARACTERISTICS (Note 5)</b>						
Drain-Source Breakdown Voltage	$BV_{DSS}$	30	-	-	V	$V_{GS} = 0V, I_D = 250\mu A$
Zero Gate Voltage Drain Current $T_J = 25^\circ\text{C}$	$I_{DSS}$	-	-	1.0	$\mu A$	$V_{DS} = 30V, V_{GS} = 0V$
Gate-Source Leakage	$I_{GSS}$	-	-	$\pm 100$	nA	$V_{GS} = \pm 20V, V_{DS} = 0V$
<b>ON CHARACTERISTICS (Note 5)</b>						
Gate Threshold Voltage	$V_{GS(th)}$	1	1.45	2.1	V	$V_{DS} = V_{GS}, I_C = 250\mu A$
Static Drain-Source On-Resistance	$R_{DS(on)}$	-	23	32	m $\Omega$	$V_{GS} = 10V, I_C = 7A$
			32	46		$V_{GS} = 4.5V, I_C = 5.6A$
Forward Transfer Admittance	$ Y_{fs} $	-	7.6	-	S	$V_{DS} = 5V, I_C = 7A$
Diode Forward Voltage (Note 5)	$V_{SD}$	-	0.7	1.0	V	$V_{GS} = 0V, I_S = 1A$
<b>DYNAMIC CHARACTERISTICS (Note 6)</b>						
Input Capacitance	$C_{iss}$	-	404.5	-	pF	$V_{DS} = 15V, V_{GS} = 0V,$ $f = 1.0\text{MHz}$
Output Capacitance	$C_{oss}$	-	51.8	-	pF	
Reverse Transfer Capacitance	$C_{rss}$	-	45.1	-	pF	
Gate Resistance	$R_g$	-	1.5	-	$\Omega$	$V_{DS} = 0V, V_{GS} = 0V, f = 1\text{MHz}$
Total Gate Charge (10V)	$Q_g$	-	9.2	-	nC	$V_{GS} = 10V, V_{DS} = 15V,$ $I_D = 5.8A$
Gate-Source Charge	$Q_{gs}$	-	1.2	-	nC	
Gate-Drain Charge	$Q_{gd}$	-	1.8	-	nC	
Turn-On Delay Time	$t_{D(on)}$	-	3.4	-	ns	$V_{GS} = 10V, V_{DS} = 15V,$ $R_G = 3\Omega, R_L = 2.6\Omega$
Turn-On Rise Time	$t_r$	-	6.18	-	ns	
Turn-Off Delay Time	$t_{D(off)}$	-	13.92	-	ns	
Turn-Off Fall Time	$t_f$	-	2.84	-	ns	

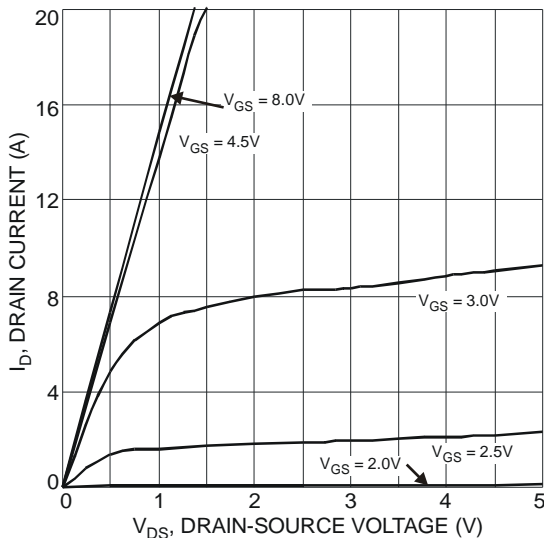


Fig. 1 Typical Output Characteristics

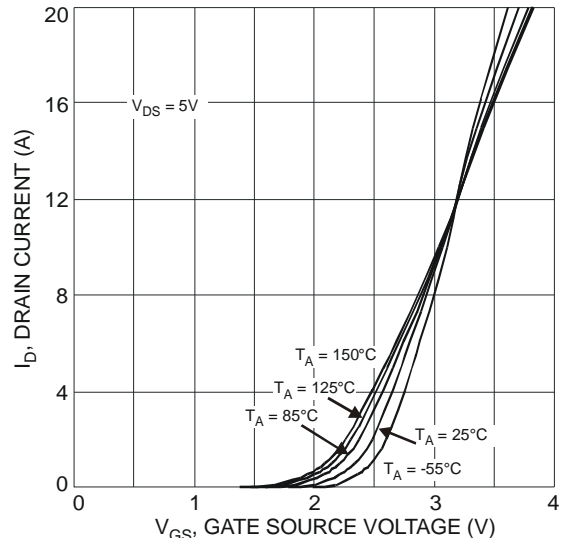


Fig. 2 Typical Transfer Characteristics

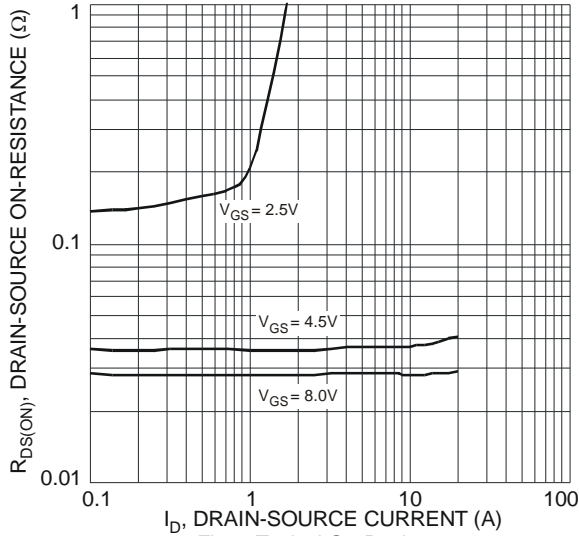


Fig. 3 Typical On-Resistance vs. Drain Current and Gate Voltage

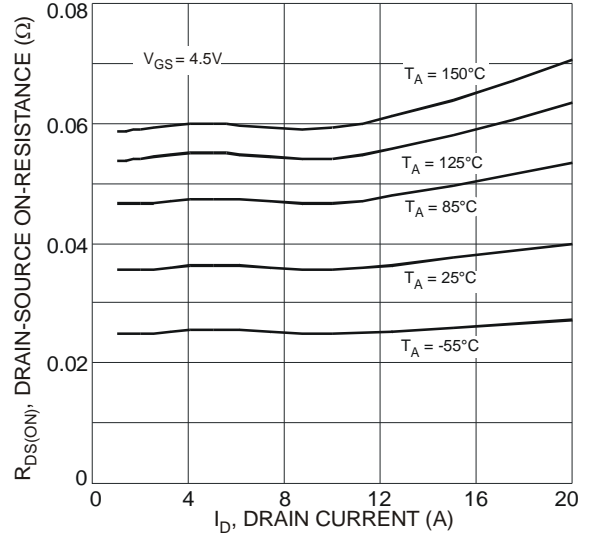


Fig. 4 Typical Drain-Source On-Resistance vs. Drain Current and Temperature

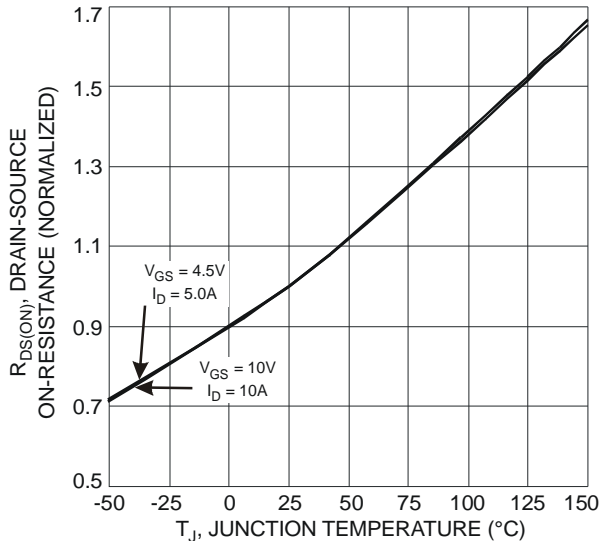


Fig. 5 On-Resistance Variation with Temperature

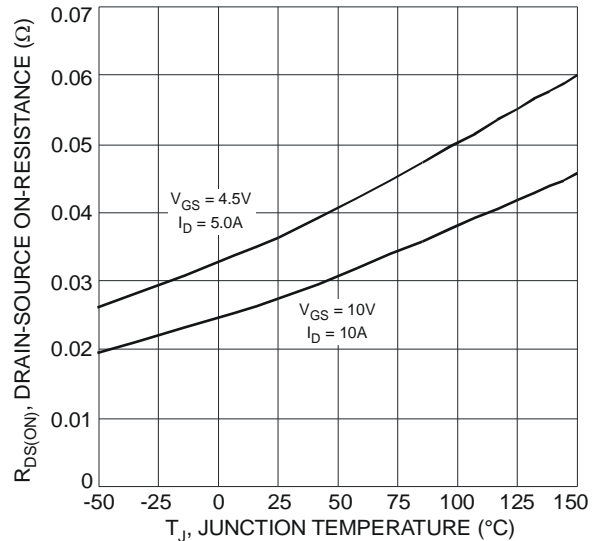


Fig. 6 On-Resistance Variation with Temperature

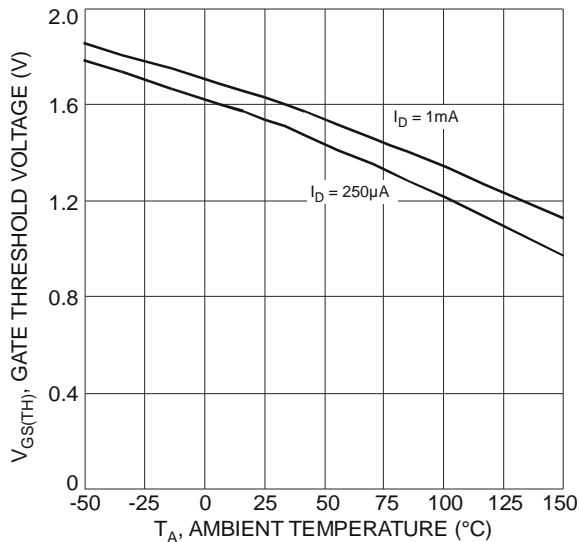


Fig. 7 Gate Threshold Variation vs. Ambient Temperature

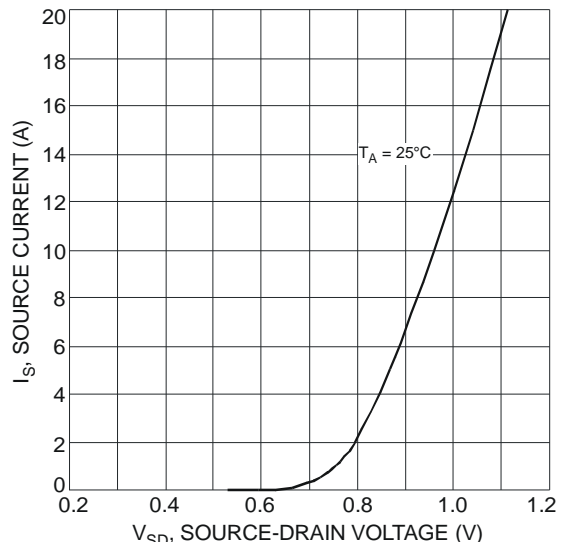


Fig. 8 Diode Forward Voltage vs. Current

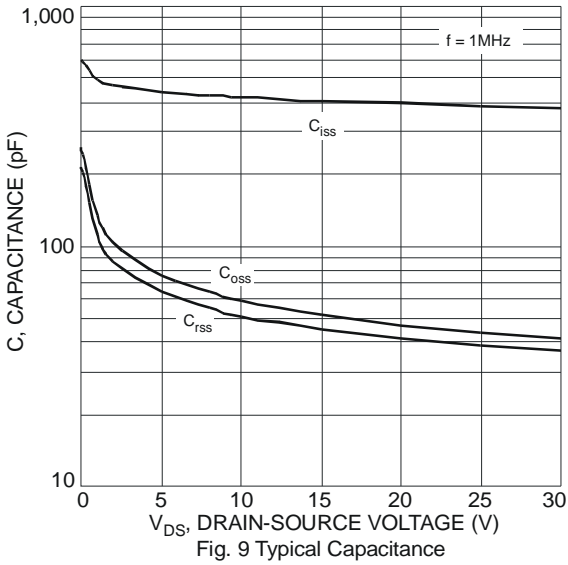


Fig. 9 Typical Capacitance

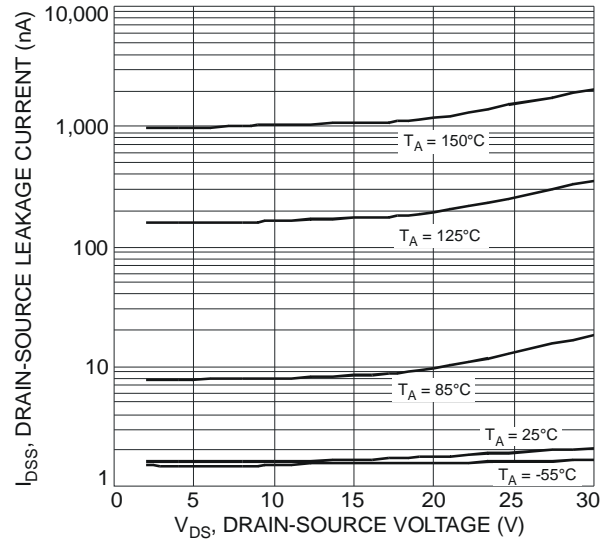


Fig. 10 Typical Drain-Source Leakage Current vs. Drain-Source Voltage

**Electrical Characteristics P-CHANNEL** @T<sub>A</sub> = 25°C unless otherwise specified

Characteristic	Symbol	Min	Typ	Max	Unit	Test Condition
<b>OFF CHARACTERISTICS (Note 5)</b>						
Drain-Source Breakdown Voltage	BV <sub>DSS</sub>	-30	-	-	V	V <sub>GS</sub> = 0V, I <sub>D</sub> = -250μA
Zero Gate Voltage Drain Current T <sub>J</sub> = 25°C	I <sub>DSS</sub>	-	-	-1.0	μA	V <sub>DS</sub> = -30V, V <sub>GS</sub> = 0V
Gate-Source Leakage	I <sub>GSS</sub>	-	-	±100	nA	V <sub>GS</sub> = ±20V, V <sub>DS</sub> = 0V
<b>ON CHARACTERISTICS (Note 5)</b>						
Gate Threshold Voltage	V <sub>GS(th)</sub>	-1	-1.7	-2.2	V	V <sub>DS</sub> = V <sub>GS</sub> , I <sub>D</sub> = -250μA
Static Drain-Source On-Resistance	R <sub>DS(on)</sub>	-	30	39	mΩ	V <sub>GS</sub> = -10V, I <sub>D</sub> = -4.3A
			42	53		V <sub>GS</sub> = -4.5V, I <sub>D</sub> = -3.7A
Forward Transfer Admittance	Y <sub>fs</sub>	-	7	-	S	V <sub>DS</sub> = -5V, I <sub>D</sub> = -4.3A
Diode Forward Voltage (Note 5)	V <sub>SD</sub>	-	-0.75	-1.0	V	V <sub>GS</sub> = 0V, I <sub>S</sub> = -1.7A
<b>DYNAMIC CHARACTERISTICS (Note 6)</b>						
Input Capacitance	C <sub>iss</sub>	-	1002	-	pF	V <sub>DS</sub> = -15V, V <sub>GS</sub> = 0V, f = 1.0MHz
Output Capacitance	C <sub>oss</sub>	-	125	-	pF	
Reverse Transfer Capacitance	C <sub>rss</sub>	-	118	-	pF	
Gate Resistance	R <sub>g</sub>	-	13	-	Ω	V <sub>DS</sub> = 0V, V <sub>GS</sub> = 0V, f = 1MHz
Total Gate Charge (4.5V)	Q <sub>g</sub>	-	10.1	-	nC	V <sub>GS</sub> = -4.5V/-10V, V <sub>DS</sub> = -15V, I <sub>D</sub> = -6A
Total Gate Charge (10V)	Q <sub>g</sub>	-	21.1	-	nC	
Gate-Source Charge	Q <sub>gs</sub>	-	2.8	-	nC	
Gate-Drain Charge	Q <sub>gd</sub>	-	3.2	-	nC	
Turn-On Delay Time	t <sub>D(on)</sub>	-	10.1	-	ns	
Turn-On Rise Time	t <sub>r</sub>	-	6.5	-	ns	V <sub>GS</sub> = -10V, V <sub>DS</sub> = -15V, R <sub>G</sub> = 6Ω, I <sub>D</sub> = -1A
Turn-Off Delay Time	t <sub>D(off)</sub>	-	50.1	-	ns	
Turn-Off Fall Time	t <sub>f</sub>	-	22.2	-	ns	

Notes: 5. Short duration pulse test used to minimize self-heating effect.  
6. Guaranteed by design. Not subject to production testing.

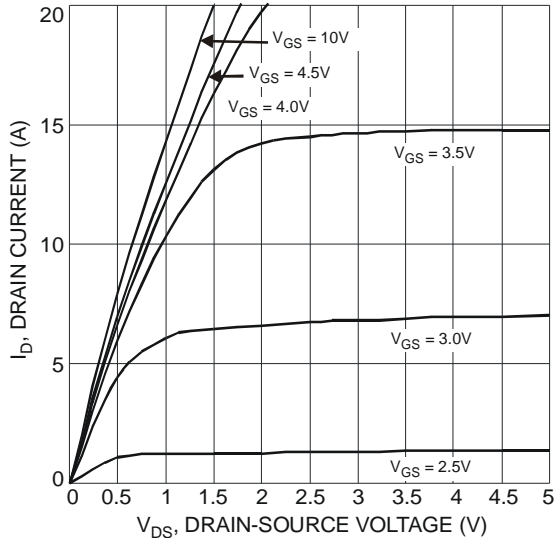


Fig. 11 Typical Output Characteristics

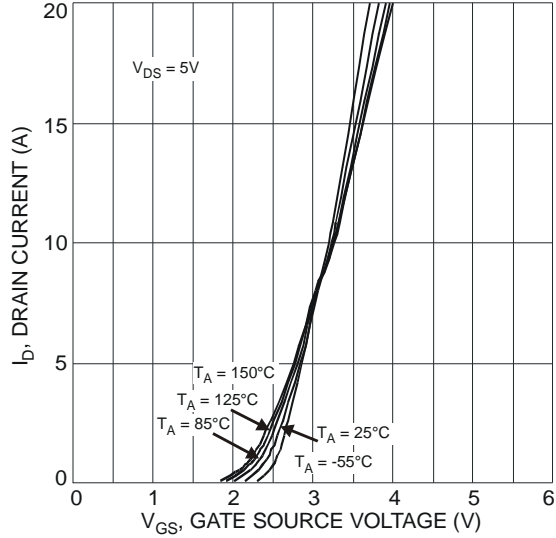


Fig. 12 Typical Transfer Characteristics

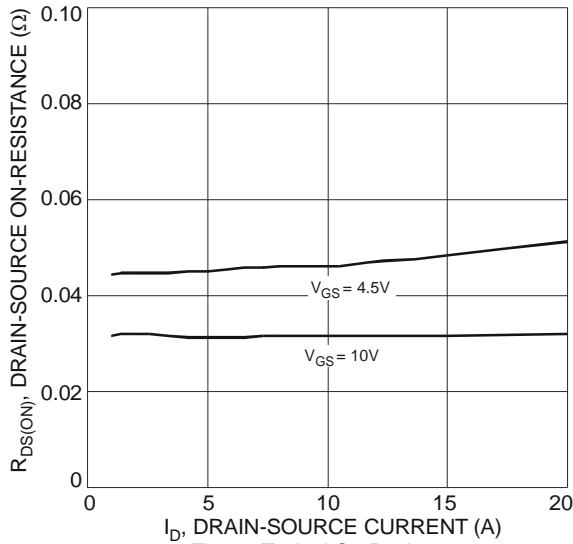


Fig. 13 Typical On-Resistance vs. Drain Current and Gate Voltage

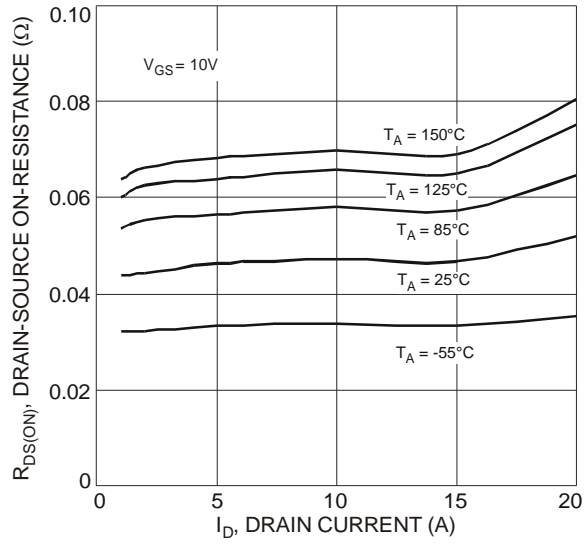


Fig. 14 Typical Drain-Source On-Resistance vs. Drain Current and Temperature

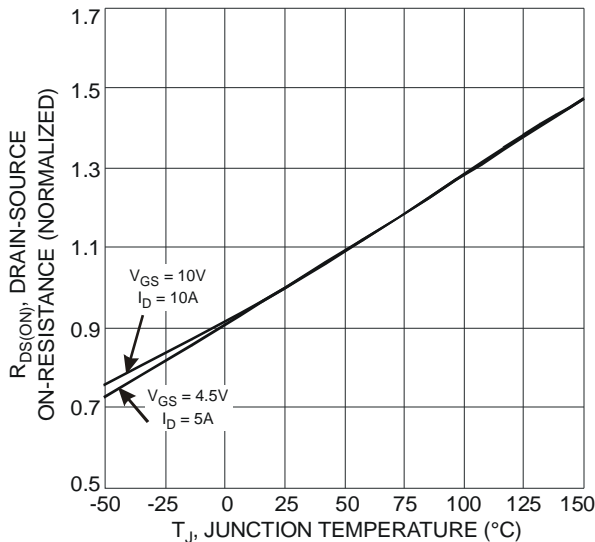


Fig. 15 On-Resistance Variation with Temperature

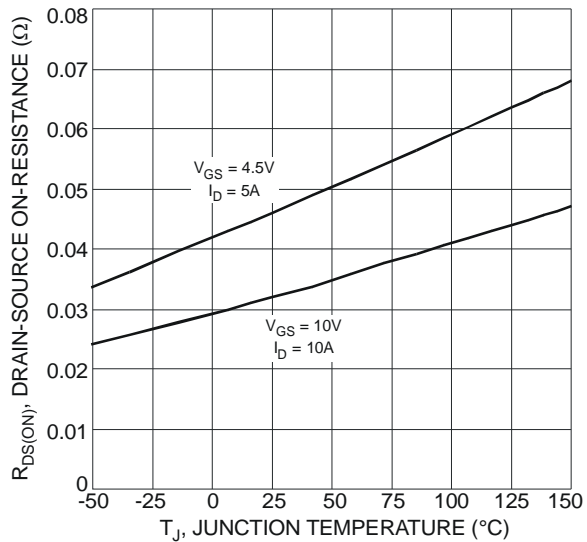


Fig. 16 On-Resistance Variation with Temperature

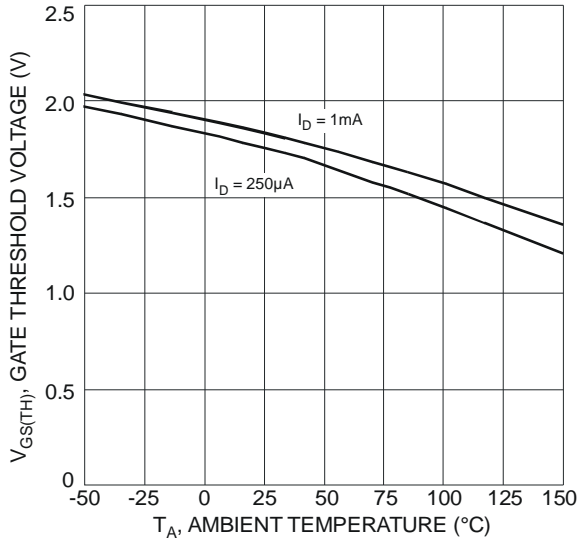


Fig. 17 Gate Threshold Variation vs. Ambient Temperature

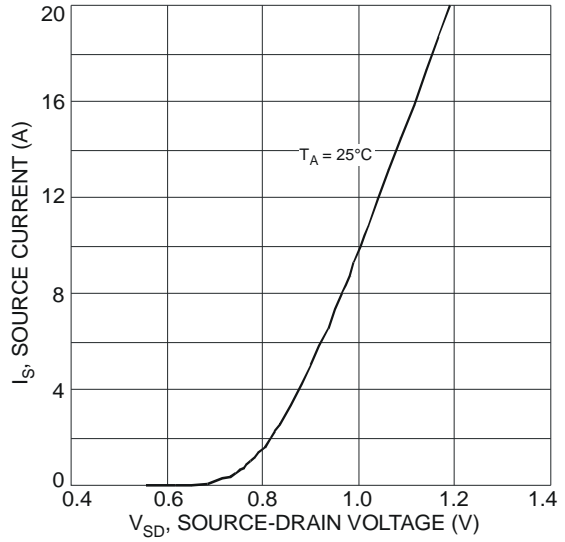


Fig. 18 Diode Forward Voltage vs. Current

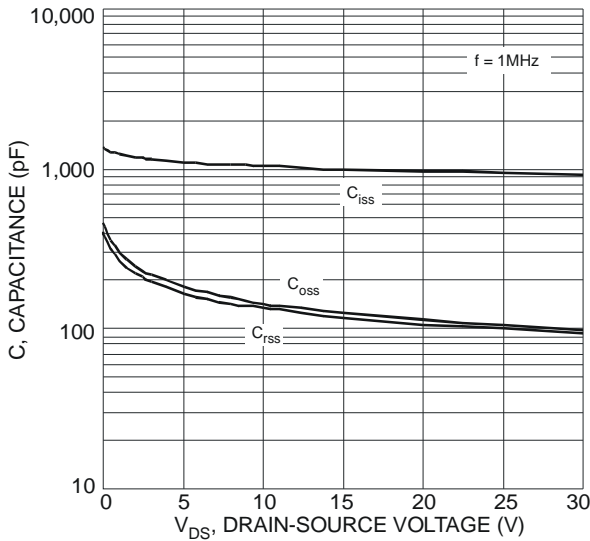


Fig. 19 Typical Capacitance

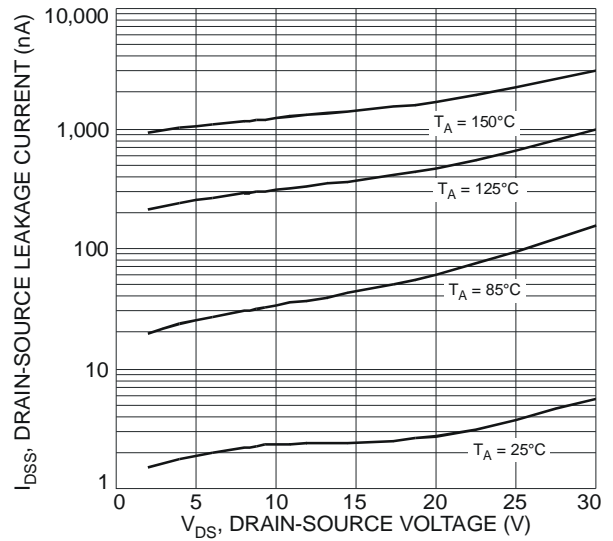


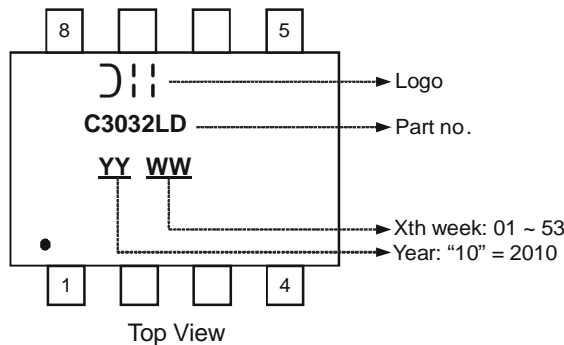
Fig. 20 Typical Drain-Source Leakage Current vs. Drain-Source Voltage

**Ordering Information** (Note 7)

Part Number	Case	Packaging
DMC3032LSD-13	SO-8	2500/Tape & Reel

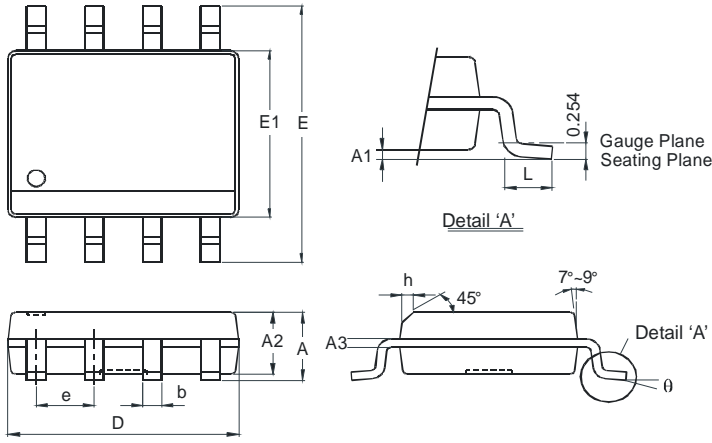
Notes: 7. For packaging details, go to our website at <http://www.diodes.com/datasheets/ap02007.pdf>.

**Marking Information**



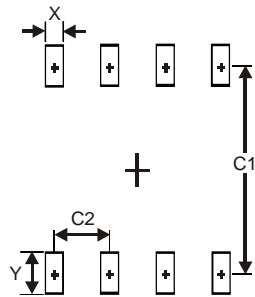
NEW PRODUCT

**Package Outline Dimensions**



SO-8		
Dim	Min	Max
<b>A</b>	-	1.75
<b>A1</b>	0.10	0.20
<b>A2</b>	1.30	1.50
<b>A3</b>	0.15	0.25
<b>b</b>	0.3	0.5
<b>D</b>	4.85	4.95
<b>E</b>	5.90	6.10
<b>E1</b>	3.85	3.95
<b>e</b>	1.27 Typ	
<b>h</b>	-	0.35
<b>L</b>	0.62	0.82
<b>θ</b>	0°	8°
All Dimensions in mm		

**Suggested Pad Layout**



Dimensions	Value (in mm)
<b>X</b>	0.60
<b>Y</b>	1.55
<b>C1</b>	5.4
<b>C2</b>	1.27

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2. support or sustain life and whose failure to perform when properly used in accordance with instructions for use provided in the labeling can be reasonably expected to result in significant injury to the user.

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